


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	AMS/18/10864	
1.3 Title of PCI	Wafer mask set conversion from PE to Stepper on BCD2S Technology in ST Ang Mo Kio (Singapore)	
1.4 Product Category	See product list	
1.5 Issue date	2018-06-20	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	MARCELI SMIALKOWSKI
2.1.2 Phone	+44 1628896277
2.1.3 Email	marceli.smialkowski@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Domenico ARRIGO,Lorenzo NASO
2.1.2 Marketing Manager	Fulvio PULICELLI,Marcello SAN BIAGIO
2.1.3 Quality Manager	Alessandro PLATINI,Jean-Marc BUGNARD

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Wafer Fab (Process)	Mask Frame : introduction of new structure or never tested structure, change of die scribe separation or scribe line width	ST Ang Mo Kio (Singapore)

4. Description of change

	Old	New
4.1 Description	Wafer diffusion using the PE equipment (PE mask)	Wafer diffusion using the Stepper equipment (Stepper mask)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change

5.1 Motivation	This change will allow us to better support the customers demand
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	With dedicated genealogy
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7. Timing / schedule

7.1 Date of qualification results	2018-04-24
7.2 Intended start of delivery	2018-07-31
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

10864 Public product.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	L6563H	
	L6563HTR	
	L6563STR	

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